## Fabrication Chart

<table>
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<tr>
<th>Finished Thickness</th>
<th>SilkScreen</th>
<th>Soldermask</th>
<th>Finshed Copper Weight</th>
</tr>
</thead>
<tbody>
<tr>
<td>0.032</td>
<td>Layer 1</td>
<td>Layer 1</td>
<td>1 oz.</td>
</tr>
<tr>
<td>0.062</td>
<td>Layer 2</td>
<td>Layer 2</td>
<td>2 oz.</td>
</tr>
<tr>
<td>0.090</td>
<td>None</td>
<td>None</td>
<td>Other</td>
</tr>
<tr>
<td>0.125</td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

### Design

- **SMD**
- **THRU HOLE**
- **MIX**

### Trace/Gap Spacing

- 0.003/0.010
- 0.006/0.007
- 0.006/0.006

### Layer Count

- Single Sided
- 2 Layer
- 4 Layer
- Other

## Notes: Unless Otherwise Specified

1. **Material:**
   - All materials, including but not limited to base laminate, bonding materials, and soldermask coatings forming the finished printed circuit board shall meet UL796 requirements and be RoHS compliant and have a flammability of UL94V-0.
   - Plastic sheet: laminated metal clad, one or two sides, base material NEMA type FR-4 or other.

2. **Base Laminate:**
   - Equivalent, Wt/g: >40 Deg C or higher, minimum composition temp (Tg) of 220 Deg C.
   - Glass epoxy resin, copper-clad in accordance with 2 layer stack-up, compliant with lead free process.

3. **Soldermask:**
   - Soldermask over bare copper (SMOB) using liquid photo-imageable soldermask in accordance with IPC-SM-826. Color: green. Minor soldermask adjustments to facilitate PCB fab and/or assembly is allowed provided no defects are created to final assembly as a result.

4. **Tolerances:**
   - Unless otherwise specified PCB tolerances shall be +/-0.005 inches, hole diameters shall be +/-0.003 inches.

5. **Plating:**
   - Holes requiring plating, see hole chart, to have 1 oz. (0.0014) min. thick copper.

6. **Finish:**
   - Plate with RoHS compliant, immersion silver preferred, immersion tin or SnAgCu. With flux flux 0.0006" to 0.0008" thick all exposed areas as coated. No active fluxes are acceptable.

7. **Legend:**
   - If required, silk screen legend(s) with white non-conductive epoxy ink.

8. **Markings:**
   - Board must bear vendor's identification code (etch or white non-conductive ink).
   - Location optional.

9. **Workmanship:**
   - Board is to be manufactured per IPC-A-600 CLASS 2 requirements or better.

10. **Documentation:**
    - PCB vendor is required to return any and all documents supplied or ultimately purchased by Texas Instruments upon completion of purchase order.

11. **Drill Sizes:**
    - Hole diameters shown are finished sizes after plating unless otherwise noted.

12. **Panel Border:**
    - Any metal in border area including part number, date code and/or revision letters must be covered with soldermask.

13. **Process Changes:**
    - No dimensional, material, or process changes are allowed without prior explicit written permission from Texas Instruments.
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